

OL-NXH1501UK

wafer level chip-scale package; 39 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	6-6-2013

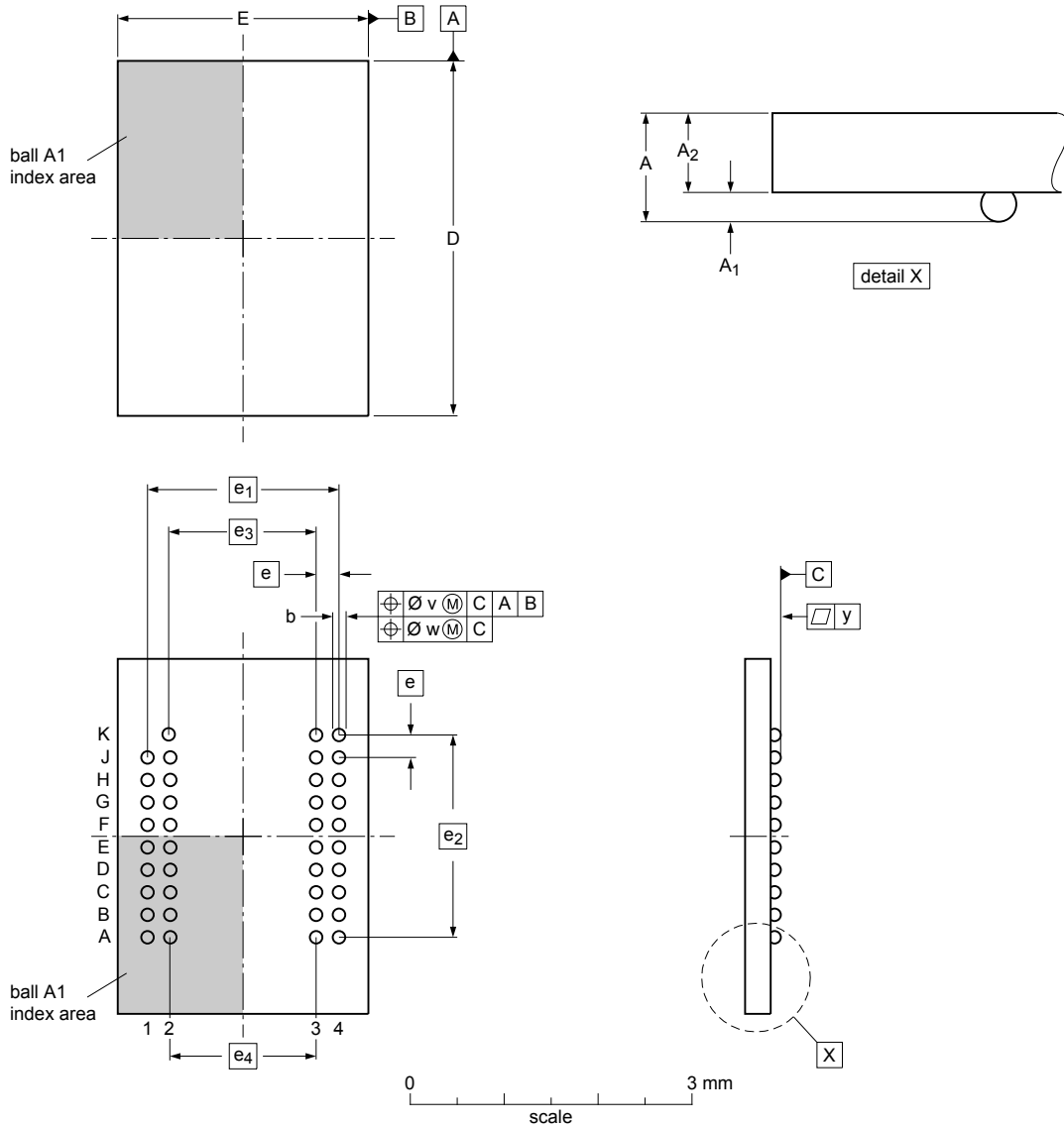
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.735	-	3.765	3.795	mm
E	package width	2.63	-	2.66	2.69	mm
A	seated height	0.34	-	0.38	0.42	mm
A ₂	package height	0.255	-	0.28	0.305	mm
e	nominal pitch	-	-	0.24	-	mm
n ₂	actual quantity of termination	-	-	39	-	



2. Package outline

WLCSP39: wafer level chip-scale package; 39 balls; 2.66 x 3.765 x 0.38 mm NXH1501UK



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	e ₃	e ₄	v	w	y
max	0.42	0.115	0.305	0.145	3.795	2.69								
nom	0.38	0.100	0.280	0.130	3.765	2.66	0.24	2.03	2.16	1.568	1.55	0.15	0.05	0.05
min	0.34	0.085	0.255	0.115	3.735	2.63								

wlcs39_nxh1501uk_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NXH1501UK					-13-05-24- 13-06-06

Fig. 1. Package outline WLCSP (OL-NXH1501UK)

3. Legal information

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